



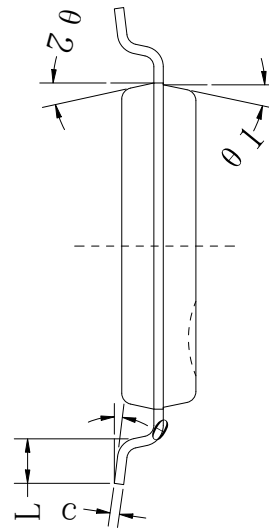
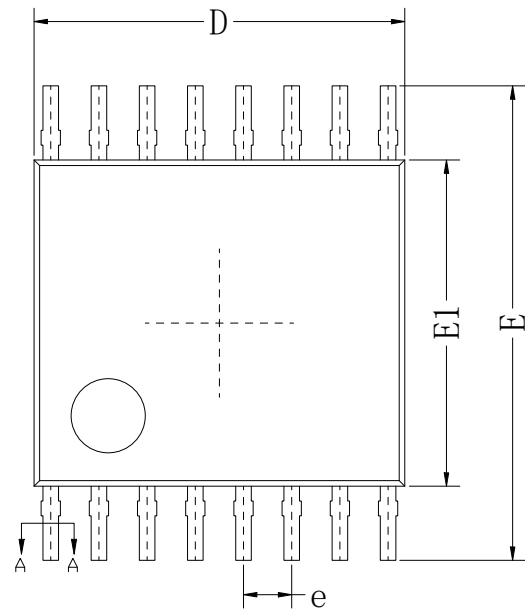
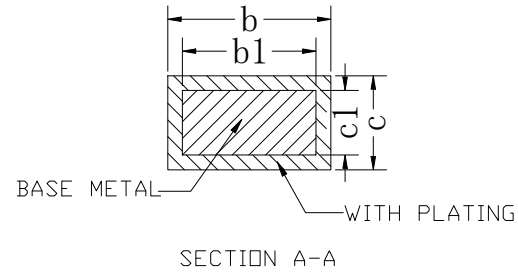
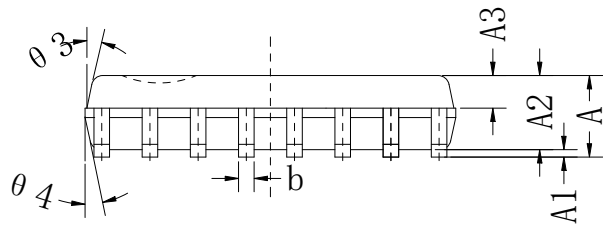
MARK



REVISION RECORD

REVISERE

APPROVER



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	--	--	1.20
A1	0.05	0.10	0.15
A2	0.80	1.00	1.05
A3	0.38	0.43	0.48
b	0.19	--	0.29
b1	0.16	0.22	0.26
c	0.13	--	0.15
c1	0.12	0.13	0.14
D	4.90	5.00	5.10
E	6.20	6.40	6.60
E1	4.30	4.40	4.50
e	0.65 (BSC)		
L	0.45	0.60	0.75
theta	0°	~	8°
theta 1	10°	~	14°
theta 2	10°	~	14°
theta 3	10°	~	14°
theta 4	10°	~	14°

技术说明:

- 1) LEADFRAME MATERIAL: COPPER;
引线框架材料: 铜;
- 2) LEADFRAME THICKNESS: 0.127mm;
引线框架厚度: 0.127mm;
- 3) BOTH PACKAGE LENGTH AND WIDTH DO NOT INCLUDE MOLD FLASH;
塑封体长度及宽度尺寸不包括塑封溢胶;
- 4) REFERENCE: JEDEC MS-013, MS-012.
参考标准: JEDEC MS-013, MS-012.

SCALE	UNIT	mm	TITLE
DATE	2024-11-07		TSSOP16L产品成型图
DESIGNER	CHECKER	APPROVER	
张金萍			DWG.NO. MT-PD-269
2024-11-07			VERSION A 第1页 共1页